

Stacking Connector

130 Position, Compression



- No solder joints, compression stacking connector
- Standardized interface for Intel Modular Interface eXtension (MIX) Bus (module to module and module to baseboard connector)
- Connector heights tailored for Multibus II environment
- 130 contacts to fully accommodate “MIX” bus signals

Date Modified: October 8, 1999

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Physical

Insulation

Material: Glass Filled Polyester (PPS)
Flammability: UL 94V-0
Color: Black
Marking: 3M Logo & Ink Stamped Part Number

Stiffner

Material: Spring Steel
Coating: Black Epoxy

Contact

Material: Beryllium Copper
Plating
Underplating: 50 μ " (1.27 μ m) Nickel — QQ-N-290, Class 2
Wiping Area: 30 μ " (0.76 μ m) Gold — MIL-G-45204, Type II, Grade C

Electrical

Current Rating: 1 A
Insulation Resistance: $> 1 \times 10^9 \Omega$ at 500 Vdc
Voltage Rating: 30 V

Environmental

Temperature Rating: -55°C to $+105^\circ\text{C}$

UL File No.: E68080

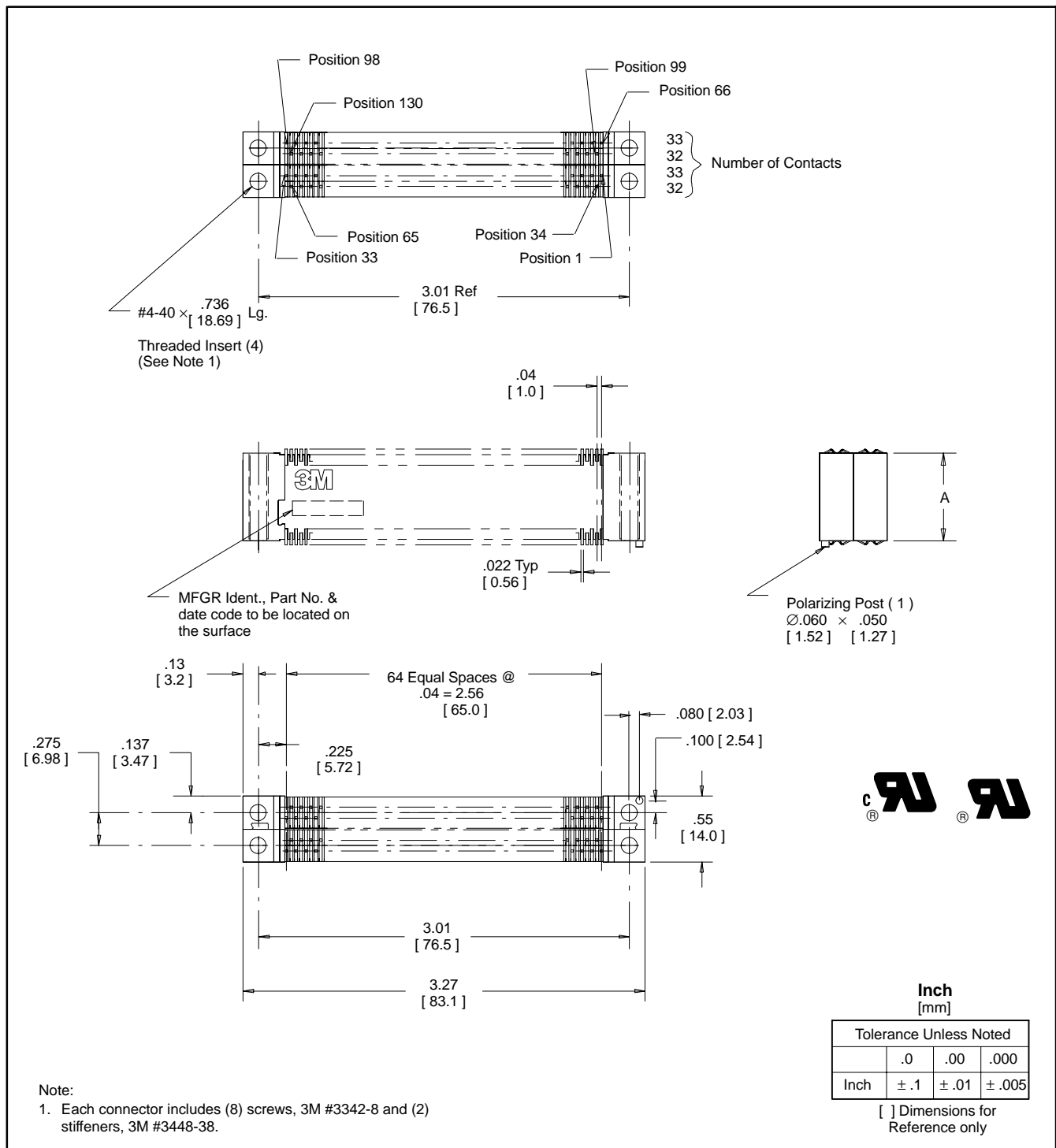
3M Interconnect Solutions Division

6801 River Place Blvd.
Austin, TX 78726-9000

For technical, sales or ordering information call
800-225-5373

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Ordering Information

388X-100A

Board spacing (Dimension A)
2 = .476 [12.09]
7 = .738 [18.75]

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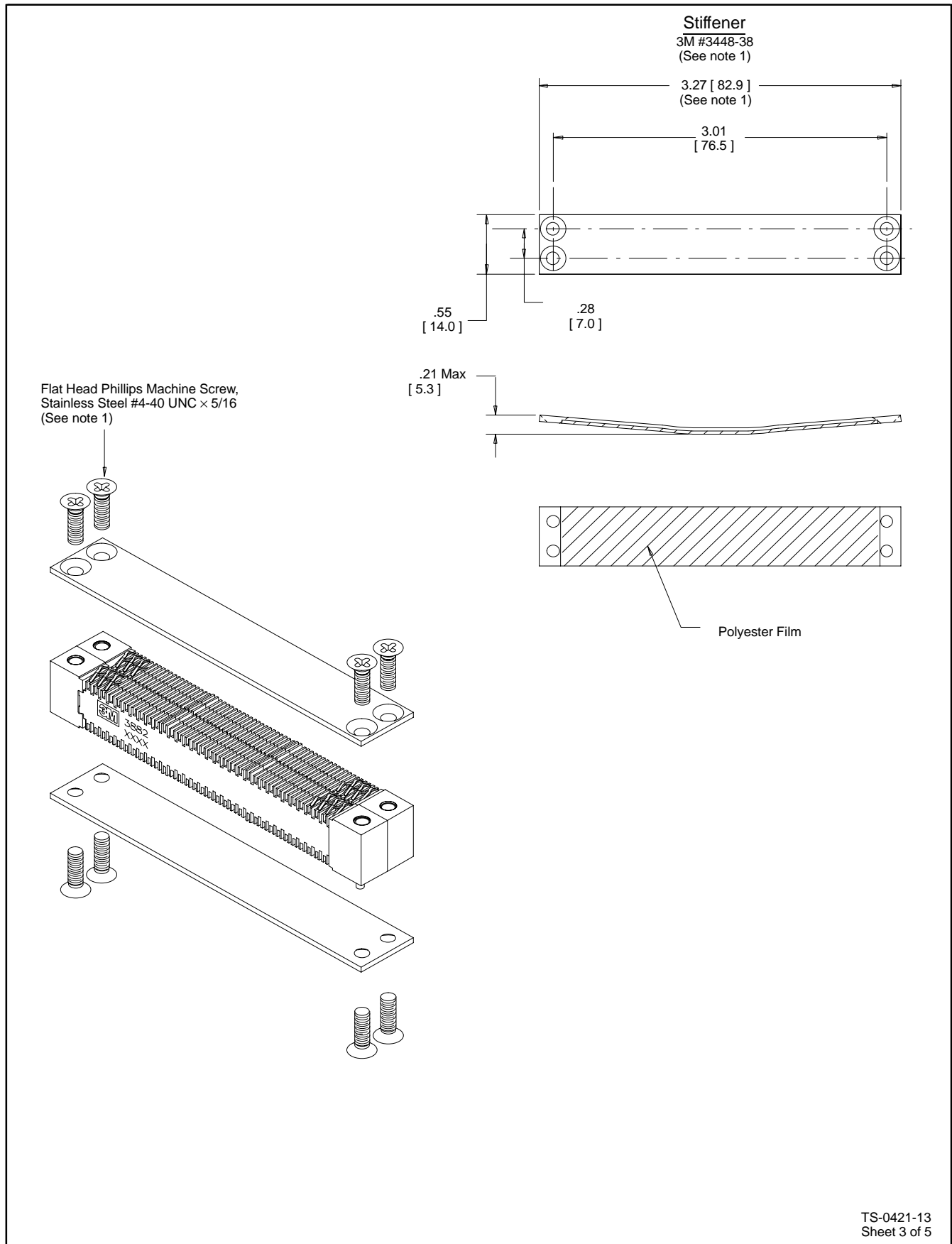
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Board and Footprint Specification

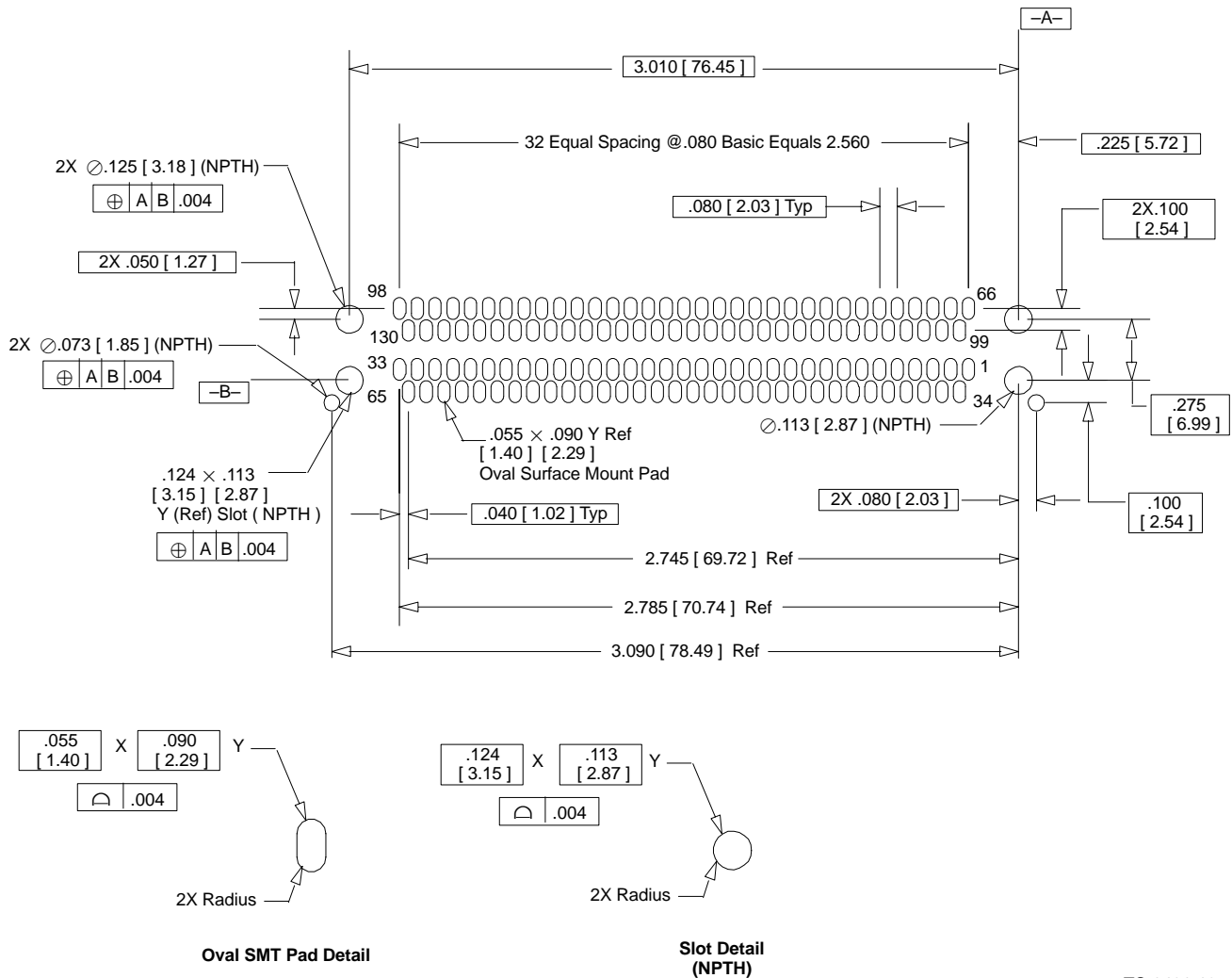
Board

Material: G10 Glass Filled Epoxy
Thickness: .062" ± .0008"

Pad

Material: 1.0 ounce Copper
Size: .055" × .090" Oval
Thickness: .0012" minimum
Underplating: 100 μ" (2.54 μm) Nickel — QQ-N-290
Plating: 30 μ" (0.76 μm) Gold — MIL-G-45204, Type II, Grade C, 130-220 Knoop hardness

**MIX Connector Footprint
 pad and hole locations
 Primary and Secondary Sides
 (Viewed from primary side)**



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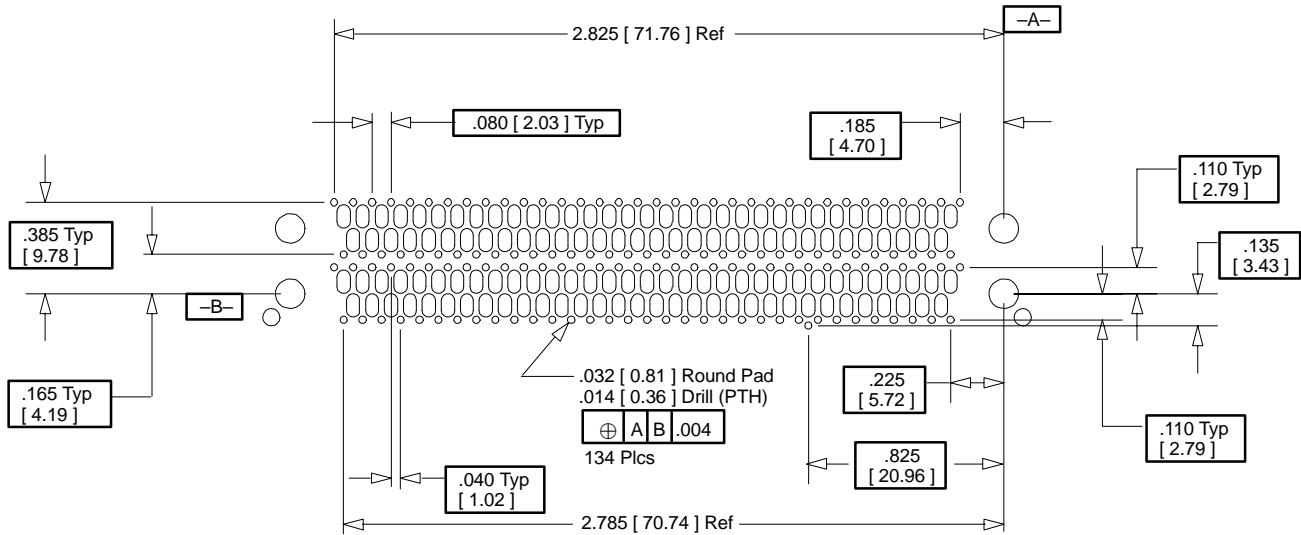
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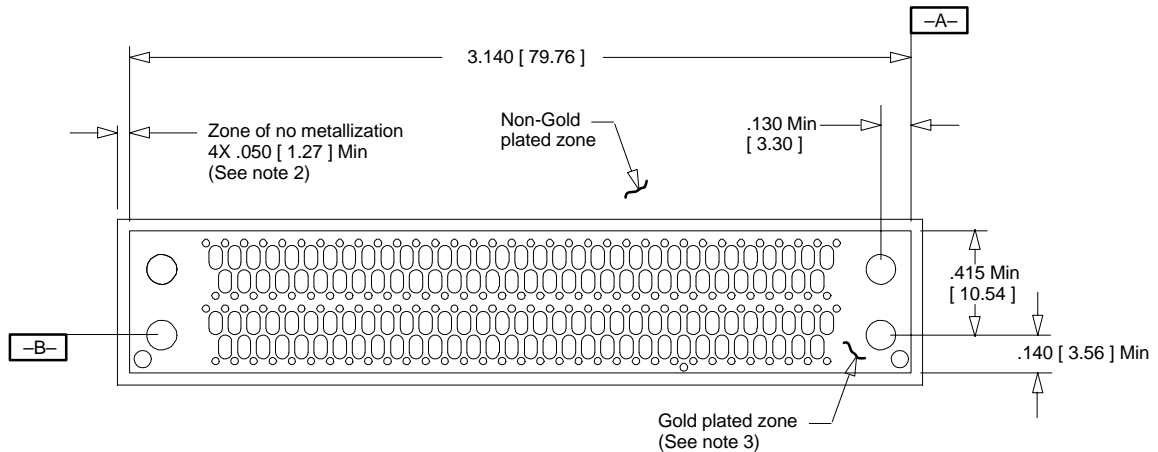
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MIX Connector Footprint
Via Locations
Primary and Secondary Sides
(Viewed from primary side)



MIX Connector Footprint
Gold and Non-Gold Zones



Notes:

2. Zone of no metallization is to be clear of any copper on the primary and secondary sides.
3. Gold plated zone is to be clear of any vias other than the established via pattern.

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